THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS



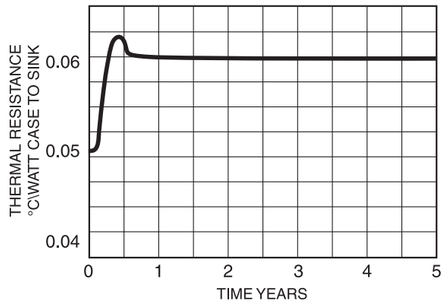
120 SERIES

The **120 Series** Silicone Oil-Based Thermal Joint Compound fills the minute air gap between mating surfaces with a grease-like material containing zinc oxide in a silicone oil carrier. It possesses an excellent thermal resistance of only 0.05°C/W for a 0.001 in. film with an area of one square inch. There is no measurable increase in case temperature of a mounted semiconductor on a heat sink after the 6-month stabilization period (Time versus Thermal Resistivity graph below).

TYPICAL VALUES FOR THERMAL RESISTANCE, CASE TO SINK (Øcs) WHEN THERMAL JOINT COMPOUNDS ARE USED		
Case Style Characteristics	Mounting Torque in inch • pounds (N•M)	Typical Thermal Resistance (°C/W)
TO-3	8 (0.9)	0.09
TO-66	9 (0.9)	0.14
TO-220	8 (0.9)	0.50
0.19 (4.8) stud x 0.44 (11.2) hex	15 (1.7)	0.16
0.25 (6.4) stud x 0.69 (17.5) hex	30 (3.39)	0.10
0.38 (9.7) stud x 1.06 (26.9) hex	75 (8.47)	0.07
0.50 (12.7) stud x 1.06 (26.9) hex	125 (14.12)	0.07
0.75 (19.1) stud x 1.25 (31.8) hex	600 (67.79)	0.052

120 SERIES - THERMAL JOINT COMPOUND	
Characteristic	Description
Volume Resistivity	5 X 10^{14} ohm-cm
Dielectric Strength	225 volts/mil
Specific Gravity	2.1 min.
Thermal Conductivity @ 36°C	0.735 W/(m)(K) 5.1(Btu) (in.)/(hr)(ft²)(°F)
Thermal Resistivity (P)	56 (°C)(in.)/watt
Bleed, % after 24 hrs @ 200°C	0.5
Evaporation, % after 24 hrs @ 200°C	0.5
Color	opaque white
Shelf life	5 years
Operating Temperature Range (°C)	-40/+200

120 SERIES - ORDER GUIDE	
Series - P/N	Container Size
120-SA	4 gram plastic pak
120-2	2 oz (0.06 kg) jar
120-5	5 oz (0.14 kg) tube
120-8	8 oz (0.23 kg) jar
120-80	5 lb (2.27 kg) can
120-320	20 lb (9.08 kg) can



HIGH PERFORMANCE THERMAL COMPOUND

122 SERIES



122 Series Thermal Joint Compound is a stable, silicone based, thixotropic paste developed to provide premium performance at an affordable price. It is formulated to significantly reduce contact thermal resistance where power densities are concentrated in devices such as flip chip, reduced die size, and 'overclock' microprocessors. When applied as a thin film between a Wakefield-Vette heat sink and device it possesses superior thermal conductivity compared to traditional 'grease'. It is compatible with automated or manual dispensing methods and is fully RoHS compliant.

122 SERIES THERMAL JOINT COMPOUND	
Typical Characteristics	Description
Appearance	Smooth Gray paste
Thermal Conductivity	2.5 W / m °K, 17.3 (Btu) (in.)/(hr) (ft²) (°F)
Thermal Resistance	0.02 °C in 2 / W
Bleed	0.015 wt%, 24 hrs at 200°C
Evaporation	0.150 wt%, 24 hrs at 200°C
Volume Resistivity	1.4 x 1010 ohm-cm
Dielectric Strength	225 volts/mil
Specific Gravity	2.23 (gm/cc) at 25°C
Operating Range	-40°C to 205°C
Shelf Life	5 years

122 SERIES - ORDER GUIDE	
Series - P/N	Container Size
122-10CC	10cc syringe
122-2	2 oz (0.06 kg) jar
122-30CC	30cc syringe

WAKEFIELDTHERMAL

THERMAL COMPOUNDS, ADHESIVES & INTERFACE MATERIALS

126 SERIES



The **126 Series** is a nontoxic, synthetic, ester-based (nonsilicone) Thermal Joint Compound with metal oxide fillers designed to enhance thermal performance characteristics of plastic and metal package devices exceeding that of silicone-based compounds. Solved are problems associated with contamination of wave solder baths and migration of silicone-based products. Shelf life: 5 years.

126 SERIES THERMAL JOINT COMPOUND	
Characteristics	Description
Appearance	Smooth, white homogeneous paste
Solids Content, wt %	65% min
Thermal Conductivity at 36°C	.69 W / m °K, 4.8 (Btu)(in.)/(hr) (ft²) (°F)
Interface Thermal Resistance	0.043°C/W TO-3 at 0.0008 thick film
Bleed, 24 hrs at 200°C, wt%	0.09% max
Evaporation, 24 hrs at 200°C, wt%	0.6 max
Volume Resistivity	2.3 x 10^{12} ohms-cm
Dielectric Strength	200 volts/mil
Specific Gravity @ 60°F	2.93 (gm/cc)
Penetration	280 to 320
Operating Range	-40°C to 200°C

126 SERIES - ORDER GUIDE	
Series - P/N	Container Size
126-2	2 oz (0.6 kg) jar
126-4	4 oz (0.11 kg) tube
126-4S	4 oz (0.11 kg) syringe
126-5LB	5 lb (2.27 kg) can



DELTABOND™ 152

DeltaBond™ 152 adhesive is ideal for general cementing; thermally bonding semiconductors and components to chassis or heat sinks, while electrically isolating one from the other; fabricating heat sinks or thermal links; and for all permanent bonding of assemblies which require high thermally conductive interfaces. It produces a rigid, high strength bond to most materials when cured. **DeltaBond™ 152** is available in bi-packs, kits, and quarts. Order one bottle of hardener A-4 or B-4 per one quart of **DeltaBond™ 152** separately. Shelf life: 152KA 1 year, all others 2 years.

DELTABOND™ 152		
Characteristics	Hardener Type	
Typical Properties Fully Cured	A4	B4
Thermal conductivity - W/(m) (°K)	0.836	0.908
(Btu) (in.)/(hr) (ft²) (°F)	5.8	6.3
Thermal resistivity - (°C) (in.) watt	47	42
Bond shear strength 77°F	2,900	2,300
1 in. overlap - psi 125°F	2,200	2,000
etched aluminum to etched aluminum 212°F	400	800
Heat distortion point - °F	130	225
Minimum dielectric strength, v/mil, 0.125 in. sample	400	400
Max operation Continuous	65	150
temp - °C Intermittent	100	190

DELTABOND™152		
Mixing Proportions and Working Properties		
Characteristics	A4	B4
Parts of hardener per 100 parts of resin by weight	7.5	3.5
*Working Time - at 77°F	45 min	30 min
†Initial cure time 77°F	8 hrs	6 hrs
150°F	45 min	30 min
250°F	20 min	15 min
‡Post-cure time at a temp in °F	4 hrs @200°F	4 hrs @ 200°F
‡Alternate room temp. aging time at 77°F	4 days	4 days
Working consistency (77°F)	viscous liquid	paste
Working viscosity (77°F) cps	25,000	—

NOTES:

* Since the hardener/resin reaction is exothermic, it is important that batch Isize be matched to hardener speed. Working times given are for approximate batch sizes: A—200 gms, B—200 gms. Larger batch sizes will greatly reduce working time.

** For optimum electrical properties, dry parts for 15 minutes at 150°F (65°C) or 30 minutes at 75°F (24°C) to slowly evaporate the thinner and then final cure for 4 hours at 275°F (135°C).

† After initial cure, material may be handled, removed from fixture, etc., but has not yet achieved full properties and should be room temperature aged or post-cured as shown to achieve full physical and electrical properties.

‡ After initial cure, material may be brought to full physical and electrical properties during post-cure or may be room temperature aged for charted length of time to achieve same full properties.

DELTABOND™152			
	Ordering Guide - Resin and Hardener		
Model Number	Resin		Hardener
	Part No.	Container	Part Number
DeltaBond™ 152	152-1A	Bi-Pack (1 oz)	Included in PIN 152-1 A ("A-4") Type
	152-1B	Bi-Pack (1 oz)	Included in P/N 152-1 B ("B-4") Type
	152-KA	Kit (7 oz Resin, 0.5 oz Hardener)	Included in P/N 152-KA
	152-Q	1 quart (4 lbs)	A-4 (0.316 lb), B-4 (0.14 lb), (order 1 only)
All hardener part numbers: A-4, B-4			

The information contained herein is based on data believed to be reliable but we do not assume responsibility for accuracy. All such information is used at the customer's own risk, conditions of use being beyond our control.